

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
650V	580mΩ@10V	6.5A

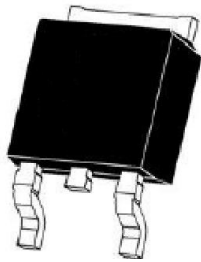
### Feature

- Super Junction high voltage MOSFET technology
- Ultra low gate charge cause lower driving requirement
- Low On-resistance and low conduction loss

### Application

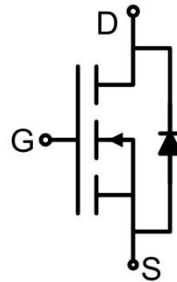
- Switching Mode Power Supplies(SMPS)
- PWM motor controls
- LED lighting
- Adapter

### Package

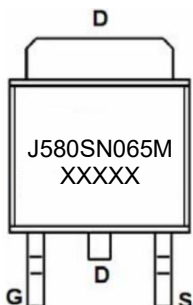


TO-252AB

### Circuit diagram



### Marking



### Absolute maximum ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>1,3)</sup> ( $V_{GS} = 10\text{V}$ )	$I_D$	6.5	A
Continuous Drain Current <sup>1,3)</sup> ( $V_{GS} = 10\text{V}$ , $T_C=100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	4.1	A
Pulsed Drain Current ( $t_p \leq 10\mu\text{s}$ )	$I_{DM}$	16	A
Single Pulse Avalanche Energy <sup>2)</sup>	$E_{AS}$	135	mJ
Power Dissipation <sup>1,3)</sup>	$P_D$	65	W
Thermal Resistance Junction to Case	$R_{\theta JC}$	1.9	$^\circ\text{C}/\text{W}$
Operating Junction Temperature	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$	650			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 650\text{V}$ , $V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 30\text{V}$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	2.6	3.4	4.2	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}$ , $I_D = 4\text{A}$		500	580	m $\Omega$
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 400\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$		400		pF
Output Capacitance	$C_{oss}$			12.9		
Reverse Transfer Capacitance	$C_{rss}$			1.9		
Total Gate Charge	$Q_g$	$V_{DS} = 400\text{V}$ , $V_{GS} = 10\text{V}$ , $I_D = 4\text{A}$		13.2		nC
Gate-Source Charge	$Q_{gs}$			2.3		
Gate-Drain Charge	$Q_{gd}$			7.1		
Turn-on delay time	$t_{d(on)}$	$V_{DS} = 400\text{V}$ , $V_{GS} = 13\text{V}$ , $I_D = 4\text{A}$ $R_G = 3\Omega$		20		nS
Turn-on rise time	$t_r$			20		
Turn-off delay time	$t_{d(off)}$			22.5		
Turn-off fall time	$t_f$			48		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$	$T_C = 25^\circ\text{C}$			6.5	A
Diode Forward voltage	$V_{SD}$	$V_{GS} = 0\text{V}$ , $I_S = 4\text{A}$			1.2	V
Reverse Recovery Time	$T_{rr}$	$V_{GS} = 0\text{V}$ , $V_R = 400\text{V}$ , $I_F = 4\text{A}$ $di/dt = -100\text{A}/\mu\text{s}$		171		nS
Reverse Recovery Charge	$Q_{rr}$			1440		nC
Peak reverse recovery current	$I_{rrm}$			17.2		A

Notes:

- 1) The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2)  $T_J = 25^\circ\text{C}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\Omega$ ,  $L = 30\text{mH}$ ,  $I_{AS} = 3\text{A}$ .
- 3) Thermal resistance from junction to soldering point (on the exposed drain pad).
- 4) Guaranteed by design, not subject to production.

## Typical Characteristics

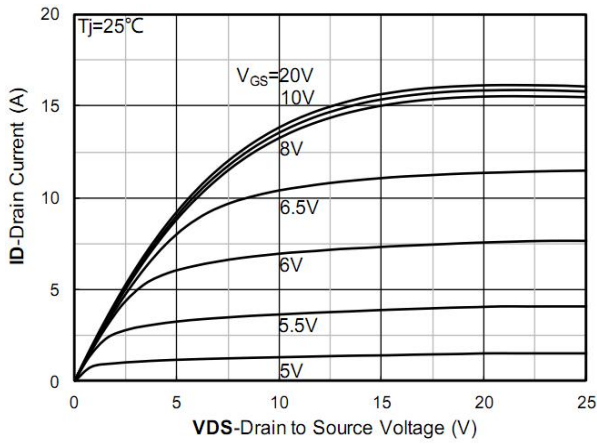


Figure 1. Output Characteristics; typical values

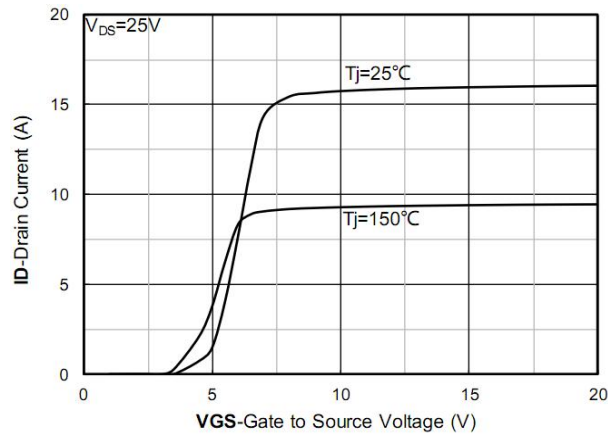


Figure 2. Transfer Characteristics; typical values

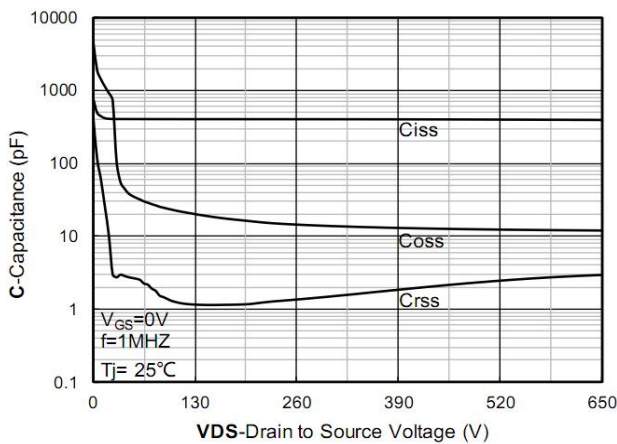


Figure 3. Capacitance Characteristics; typical values

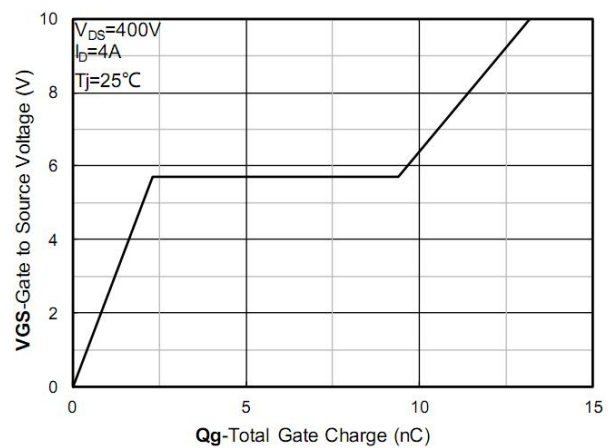


Figure 4. Gate Charge; typical values

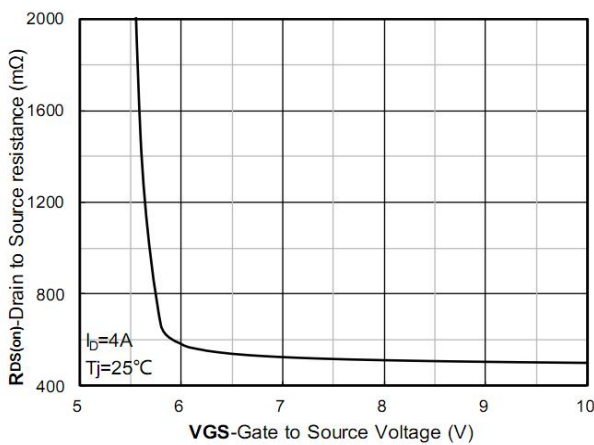


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

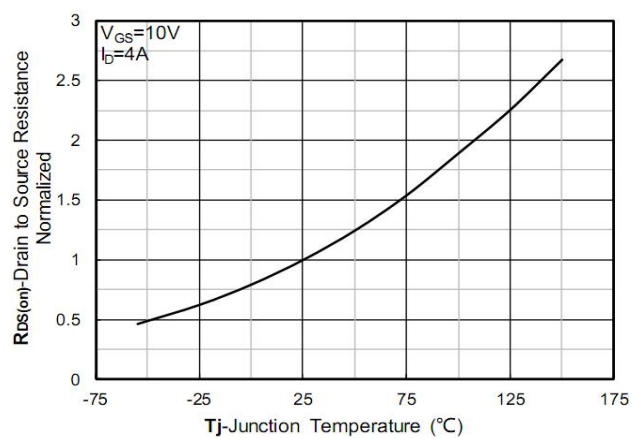


Figure 6. Normalized On-Resistance

## Typical Characteristics

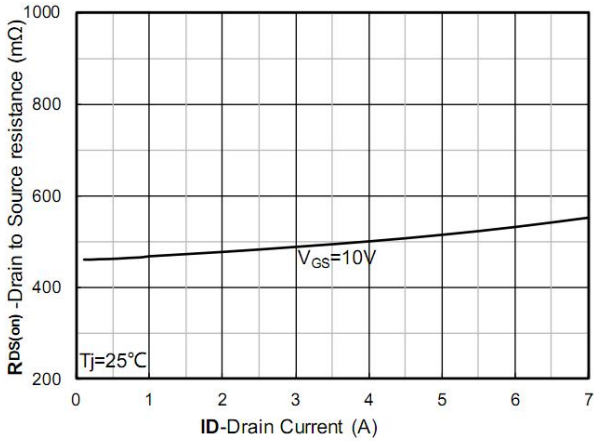


Figure 7.  $R_{DS(on)}$  vs. Drain Current; typical values

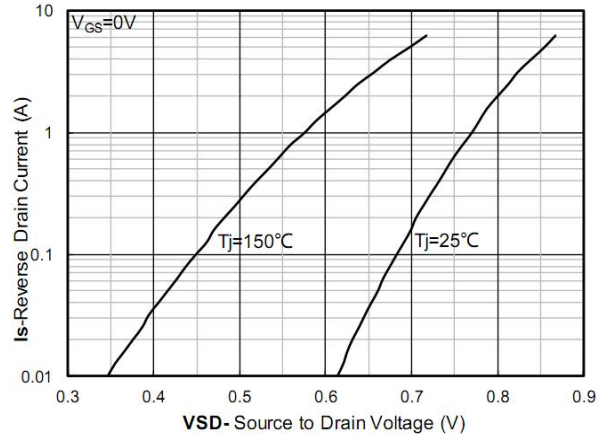


Figure 8. Forward characteristics of reverse diode; typical values

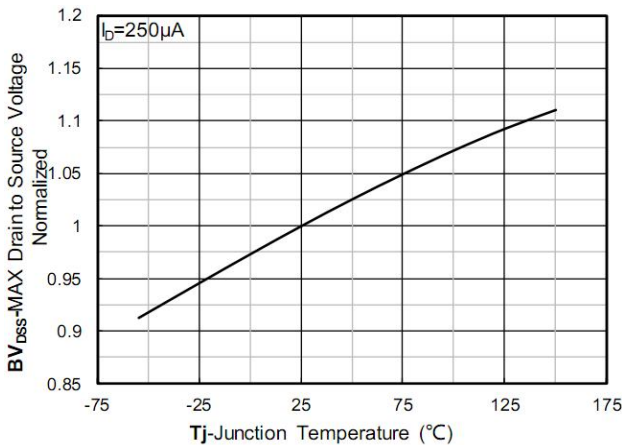


Figure 9. Normalized breakdown voltage

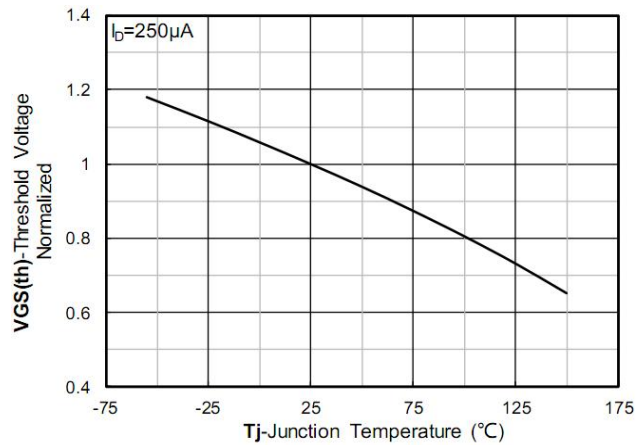


Figure 10. Normalized Threshold voltage

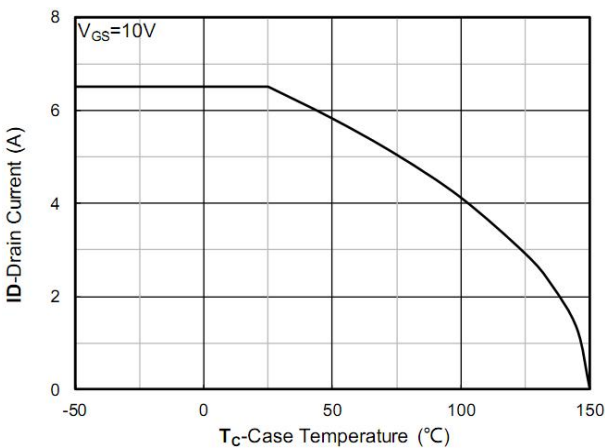


Figure 11. Current dissipation

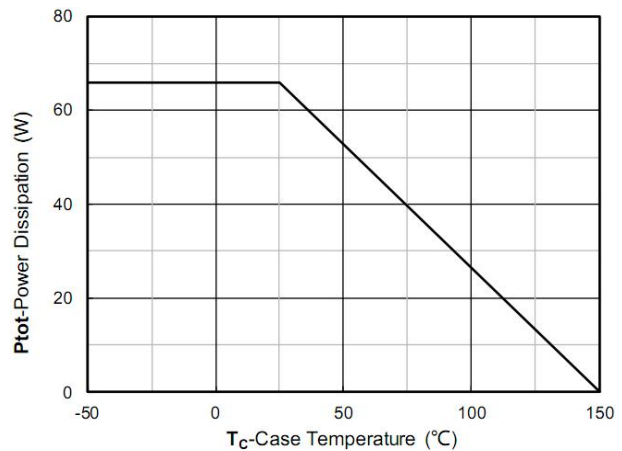


Figure 12. Power dissipation

## Typical Characteristics

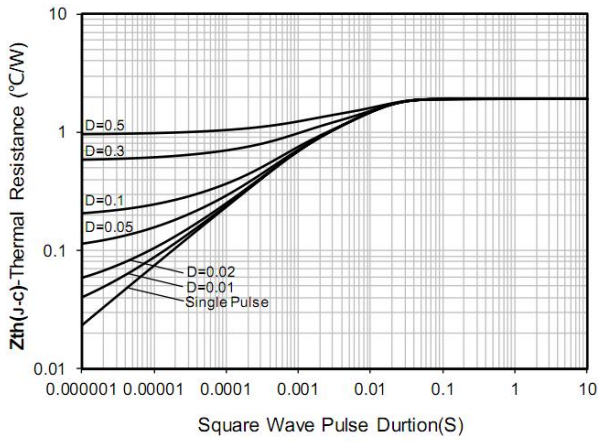


Figure 13. Maximum Transient Thermal Impedance

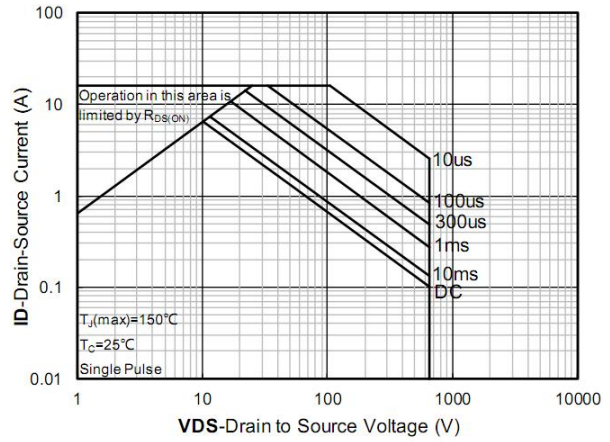
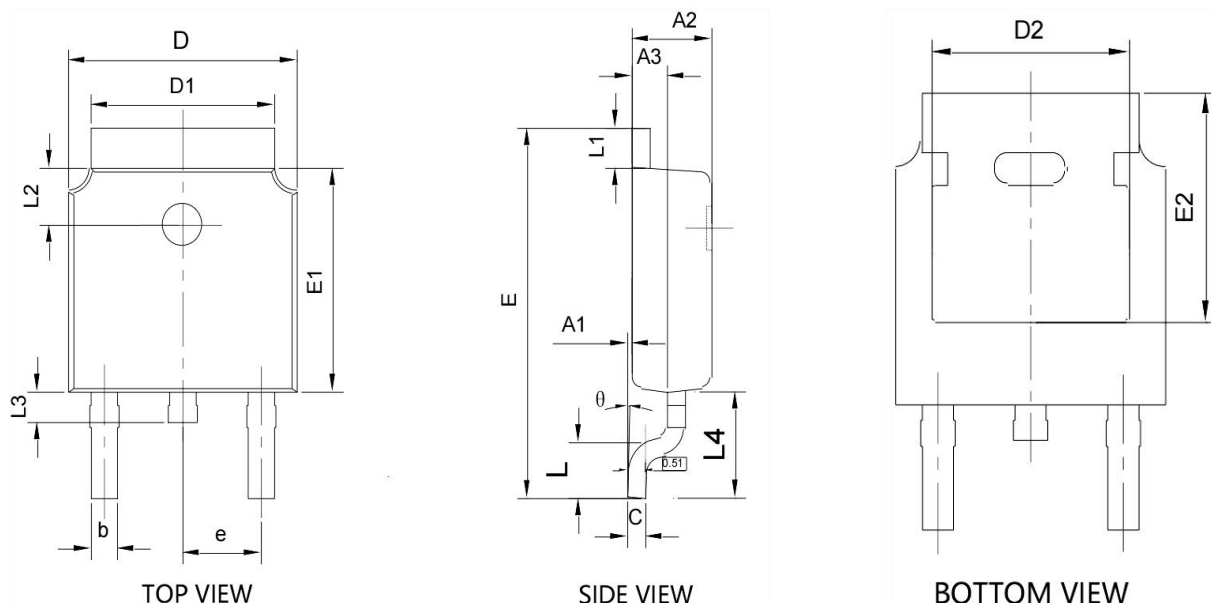


Figure 14. Safe Operation Area

### TO-252AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A1	0.000	0.200	0.000	0.008
A2	2.200	2.400	0.087	0.094
A3	0.900	1.100	0.035	0.043
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.150	5.450	0.203	0.215
D2	4.600	4.950	0.181	0.195
E	9.900	10.300	0.390	0.406
E1	6.000	6.200	0.236	0.244
E2	5.150	5.450	0.203	0.215
e	2.286 BSC.		0.090 BSC.	
L	1.250	1.750	0.049	0.069
L1	0.900	1.270	0.035	0.050
L2	1.400	1.900	0.055	0.075
L3	0.600	1.000	0.024	0.039
L4	2.900 REF.		0.114 REF.	
$\theta$	0°	10°	0°	10°